Simulation Methods For Esd Protection Development By Harald Gossner

This comprehensive and insightful book discusses ESD protection circuit design problems from an IC designer's perspective. On-Chip ESD Protection for Integrated Circuits: An IC Design Perspective provides both fundamental and advanced materials needed by a circuit designer for designing ESD protection circuits, including: Testing models and standards adopted by U.S. Department of Defense, EIA/JEDEC, ESD Association, Automotive Electronics Council, International Electrotechnical Commission, etc. ESD failure analysis, protection devices, and protection of sub-circuits Whole-chip ESD protection and ESD-to-circuit interactions Advanced low-parasitic compact ESD protection structures for RF and mixed-signal IC's Mixed-mode ESD simulation-design methodologies for design prediction ESD-to-circuit interactions, and more! Many real world ESD protection circuit design examples are provided. The book can be used as a reference book for working IC designers and as a textbook for students in the IC design field.

This book on electrostatic discharge phenomena is essentially a translation and update ofa Swedish edition from 1992. The book is intended for people working with electronic circuits and equipments, in application and development. All personnel should be aware of the ESD-hazards, especially those responsible for quality. ESD-prevention is a part of TQM (Total Quality Management). The book is also usable for courses on the subject. Background It was soon realised that the MOS-circuits (MOS=Metal Oxide Semiconductor), which appeared in the beginning of the 1960-ties were sensitive to electrostatic discharges. But a severe accident accelerated the search for materials that do not generate electric charges. In April 1964 three people were working inside a satellite at Cape Kennedy Space Center. They suddenly screamed "we are burning". They died. The satellite incapsulation was covered with untreated plastics to protect against dust. When the plastics was pulled off both this and the metal incapsulating got charged. A discharge from the metal ignited inflammable parts of the satellite. Eleven more people were injured and the cost of the accident amounted to about 55 billions USD.

This book addresses the increasing demands from the industrial electronic engineers for reference materials on both theories and hands-on design skills for electrostatic discharge (ESD) protection designs, and the needs from college students to learn the same for their future career. Based on the author’s 25+ years of design and teaching experience, and research outcomes on the topic, this book is structured to cover all important aspects for on-chip ESD protection designs for integrated circuits (ICs), from theories to design skills to computer-aided design (CAD) methods, covering ESD phenomena, ESD failures, ESD test models, ESD protection devices, ESD protection circuits, ESD co-design methodology for high-performance mixed-signal ICs and broadband radio-frequency (RF) ICs, and more.

Failures caused by electrostatic discharges (ESD) constitute a major problem concerning the reliability and robustness of integrated circuits and electronic systems. This book summarizes the many diverse methodologies aimed at ESD protection and shows, through a number of concrete studies, that the best approach in terms of robustness and cost-effectiveness consists of

implementing a global strategy of ESD protection. ESD Protection Methodologies begins by exploring the various normalized test techniques that are used to qualify ESD robustness as well as characterization and defect localization methods aimed at implementing corrective measures. Due to the increasing complexity of integrated circuits, it is important to be able to provide a simulation in which the implemented ESD protection strategy provides the desired protection, while not harming the performance levels of the circuit. Therefore, the main features and difficulties related to the different types of simulation, finite element, SPICE-type and behavioral, are then studied. To conclude, several case studies are presented which provide real-life examples of the approaches explained in the previous chapters and validate a number of the strategies from component to system level. Provides a global ESD protection approach from component to system, including both the proposal of investigation techniques and predictive simulation methodologies Addresses circuit and system designers as well as failure analysis engineers Provides the description of specifically developed investigation techniques and the application of the proposed methodologies to real case studies

ESD Protection Device and Circuit Design for Advanced CMOS Technologies is intended for practicing engineers working in the areas of circuit design, VLSI reliability and testing domains. As the problems associated with ESD failures and yield losses become significant in the modern semiconductor industry, the demand for graduates with a basic knowledge of ESD is also increasing. Today, there is a significant demand to educate the circuits design and reliability teams on ESD issues. This book makes an attempt to address the ESD design and implementation in a systematic manner. A design procedure involving device simulators as well as circuit simulator is employed to optimize device and circuit parameters for optimal ESD as well as circuit performance. This methodology, described in ESD Protection Device and Circuit Design for Advanced CMOS Technologies has resulted in several successful ESD circuit design with excellent silicon results and demonstrates its strengths.

Electrical Overstress (EOS) continues to impact semiconductor manufacturing, semiconductor components and systems as technologies scale from micro- to nano-electronics. This bookteaches the fundamentals of electrical overstress and how to minimize and mitigate EOS failures. The text provides a clear picture of EOS phenomena, EOS origins, EOS sources, EOS physics, EOS failure mechanisms, and EOS on-chip and system design. It provides an illuminating insight into the sources of EOS in manufacturing, integration of on-chip, and system level EOS protection networks, followed by examples in specific technologies, circuits, and chips. The book is unique in covering the EOS manufacturing issues from on-chip design and electronic design automation to factory-level EOS program management in today’s modern world. Look inside for extensive coverage on: Fundamentals of electrical overstress, from EOS physics, EOS time scales, safe operating area (SOA), to physical models for EOS phenomena EOS sources in today’s semiconductor manufacturing environment, and EOS program management, handling and EOS auditing processing to avoid EOS failures EOS failures in both semiconductor devices, circuits and system Discussion of how to distinguish between EOS events, and electrostatic discharge (ESD) events (e.g. such as human body model (HBM), charged device model (CDM), cable discharge events (CDM), charged board events (CBE), to system level IEC 61000-4-2 test

events) EOS protection on-chip design practices and how they differ from ESD protection networks and solutions Discussion of EOS system level concerns in printed circuit boards (PCB), and manufacturing equipment Examples of EOS issues in state-of-the-art digital, analog and power technologies including CMOS, LDMOS, and BCD EOS design rule checking (DRC), LVS, and ERC electronic design automation (EDA) and how it is distinct from ESD EDA systems EOS testing and qualification techniques, and Practical off-chip ESD protection and system level solutions to provide more robust systems Electrical Overstress (EOS): Devices, Circuits and Systems is a continuation of the author's series of books on ESD protection. It is an essential reference and a useful insight into the issues that confront modern technology as we enter the nano-electronic era.

The goal of putting `systems on a chip' has been a difficult challenge that is only recently being met. Since the world is `analog', putting systems on a chip requires putting analog interfaces on the same chip as digital processing functions. Since some processing functions are accomplished more efficiently in analog circuitry, chips with a large amount of analog and digital circuitry are being designed. Whether a small amount of analog circuitry is combined with varying amounts of digital circuitry or the other way around, the problem encountered in marrying analog and digital circuitry are the same but with different scope. Some of the most prevalent problems are chip/package capacitive and inductive coupling, ringing on the RLC tuned circuits that form the chip/package power supply rails and off-chip drivers and receivers, coupling between circuits through the chip substrate bulk, and radiated emissions from the chip/package interconnects. To aggravate the problems of designers who have to deal with the complexity of mixed-signal coupling there is a lack of verification techniques to simulate the problem. In addition to considering RLC models for the various chip/package/board level parasitics, mixed-signal circuit designers must also model coupling through the common substrate when simulating ICs to obtain an accurate estimate of coupled noise in their designs. Unfortunately, accurate simulation of substrate coupling has only recently begun to receive attention, and techniques for the same are not widely known. Simulation Techniques and Solutions for Mixed-Signal Coupling in Integrated Circuits addresses two major issues of the mixed-signal coupling problem -- how to simulate it and how to overcome it. It identifies some of the problems that will be encountered, gives examples of actual hardware experiences, offers simulation techniques, and suggests possible solutions. Readers of this book should come away with a clear directive to simulate their design for interactions prior to building the design, versus a `build it and see' mentality.

This book brings together contributions from experts in the fields to describe the current status of important topics in solid-state circuit technologies. It consists of 20 chapters which are grouped under the following categories: general information, circuits and devices, materials, and characterization techniques. These chapters have been written by renowned experts in the respective fields making this book valuable to the integrated circuits and materials science

communities. It is intended for a diverse readership including electrical engineers and material scientists in the industry and academic institutions. Readers will be able to familiarize themselves with the latest technologies in the various fields.
Electrostatic discharge (ESD) continues to impact semiconductor components and systems as technologies scale from micro- to nano-electronics. This book studies electrical overstress, ESD, and latchup from a whole-chip ESD design synthesis approach. It provides a clear insight into the integration of ESD protection networks from a generalist perspective, followed by examples in specific technologies, circuits, and chips. Uniquely both the semiconductor chip integration issues and floorplanning of ESD networks are covered from a ‘top-down' design approach. Look inside for extensive coverage on: integration of cores, power bussing, and signal pins in DRAM, SRAM, CMOS image processing chips, microprocessors, analog products, RF components and how the integration influences ESD design and integration architecturing of mixed voltage, mixed signal, to RF design for ESD analysis floorplanning for peripheral and core I/O designs, and the implications on ESD and latchup guard ring integration for both a ‘bottom-up' and ‘top-down' methodology addressing I/O guard rings, ESD guard rings, I/O to I/O, and I/O to core classification of ESD power clamps and ESD signal pin circuitry, and how to make the correct choice for a given semiconductor chip examples of ESD design for the state-of-the-art technologies discussed, including CMOS, BiCMOS, silicon on insulator (SOI), bipolar technology, high voltage CMOS (HVCMOS), RF CMOS, and smart power practical methods for the understanding of ESD circuit power distribution, ground rule development, internal bus distribution, current path analysis, quality metrics ESD: Design and Synthesis is a continuation of the author's series of books on ESD protection. It is an essential reference for: ESD, circuit, and semiconductor engineers; design synthesis team leaders; layout design, characterisation, floorplanning, test and reliability engineers; technicians; and groundrule and test site developers in the manufacturing and design of semiconductor chips. It is also useful for graduate and undergraduate students in electrical engineering, semiconductor sciences, and manufacturing sciences, and on courses involving the design of ESD devices, chips and systems. This book offers a useful insight into the issues that confront modern technology as we enter the nano-electronic era.
A thorough and concise treatment of ESD Recognizing its methodic, step-by-step attack of theelectrostatic discharge (ESD) problem, the initial release of thisbook was quoted by specialists as "the most thorough and concisetreatment of the broad ESD continuum that is available." Now in itsThird Edition, this book delivers the same trusted coverageof the topic while also incorporating recent technological advancesthat have taken place in the engineering community. The book beginswith the basics of ESD for humans and objects, and goes on tocover: Effects of ESD coupled to electronics Principal ESD specifications ESD diagnostics and testing Design for ESD immunity To help with troubleshooting, many ESD case histories are givenalong with their successful fixes. Electrostatic Dischargeis essential reading for all designers

who want to avoid componentfailures, no trouble found incidents, and random errors.

An authoritative single-volume reference on the design and testing of electrostatic discharge (ESD) structures Electrostatic discharge (ESD) is a serious challenge to the reliability of semiconductors, integrated circuits (ICs), and microelectronic systems—on-chip ESD protection is a vital component of smartphones, laptops, tablets, and other electronic devices. Practical ESD Protection Design provides comprehensive and systematic guidance on all major aspects of on-chip ESD protection for integrated circuits (ICs). Written for students and practicing engineers alike, this one-stop resource covers essential theories, hands-on design skills, computer-aided design (CAD) methods, ESD failure testing and analysis, and more. Detailed chapters examine an array of topics ranging from fundamental to advanced, including ESD phenomena, ESD protection devices and circuits, ESD design layout and technology effects, emerging ESD protection designs, and circuit simulation modelling. Based on the author's decades of design, teaching, and research experience, Practical ESD Protection Design: Features numerous real-world examples of electrostatic discharge (ESD) protection designs and skills Describes the design methodology for high-performance mixed-signal ICs and broadband radio-frequency (RF) ICs Discusses CAD-based ESD protection design using existing tools such as Technology Computer-Aided Design (TCAD) and SPICE simulation Addresses new ESD CAD algorithms and tools for full-chip ESD physical design verification Explores the disruptive future outlook of ESD protection Practical ESD Protection Design is a valuable reference for industrial engineers and academic researchers in the field, and an excellent textbook for electronic engineering courses in semiconductor microelectronics and integrated circuit design.

Electrostatic discharge (ESD) is one of the most prevalent threats to electronic components. In an ESD event, a finite amount of charge is transferred from one object (i.e., human body) to another (i.e., microchip). This process can result in a very high current passing through the microchip within a very short period of time. Thus, more than 35 percent of single-event chip damages can be attributed to ESD events, and designing ESD structures to protect integrated circuits against the ESD stresses is a high priority in the semiconductor industry. Electrostatic Discharge Protection: Advances and Applications delivers timely coverage of component- and system-level ESD protection for semiconductor devices and integrated circuits. Bringing together contributions from internationally respected researchers and engineers with expertise in ESD design, optimization, modeling, simulation, and characterization, this book bridges the gap between theory and practice to offer valuable insight into the state of the art of ESD protection. Amply illustrated with tables, figures, and case studies, the text: Instills a deeper understanding of ESD events and ESD protection design principles Examines vital processes including Si CMOS, Si BCD, Si SOI, and GaN technologies Addresses important aspects pertinent to the modeling and simulation of ESD protection solutions Electrostatic Discharge Protection: Advances and

Applications provides a single source for cutting-edge information vital to the research and development of effective, robust ESD protection solutions for semiconductor devices and integrated circuits.

Electrostatic Discharge is a pervasive issue in the semiconductor industry affecting both manufacturers and users of semiconductors. This easy-to-read, practical handbook presents an overview of ESD as it effects electronic circuits and provides a concise introduction for students, engineers, circuit designers and failure analysts.

This volume contains the proceedings of the 10th edition of the International Conference on Simulation of Semiconductor Processes and Devices (SISPAD 2004), held in Munich, Germany, on September 2-4, 2004. The conference program included 7 invited plenary lectures and 82 contributed papers for oral or poster presentation, which were carefully selected out of a total of 151 abstracts submitted from 14 countries around the world. Like the previous meetings, SISPAD 2004 provided a world-wide forum for the presentation and discussion of recent advances and developments in the theoretical description, physical modeling and numerical simulation and analysis of semiconductor fabrication processes, device operation and system performance. The variety of topics covered by the conference contributions reflects the physical effects and technological problems encountered in consequence of the progressively shrinking device dimensions and the ever-growing complexity in device technology.

An effective and cost efficient protection of electronic system against ESD stress pulses specified by IEC 61000-4-2 is paramount for any system design. This pioneering book presents the collective knowledge of system designers and system testing experts and state-of-the-art techniques for achieving efficient system-level ESD protection, with minimum impact on the system performance. All categories of system failures ranging from 'hard' to 'soft' types are considered to review simulation and tool applications that can be used. The principal focus of System Level ESD Co-Design is defining and establishing the importance of co-design efforts from both IC supplier and system builder perspectives. ESD designers often face challenges in meeting customers' system-level ESD requirements and, therefore, a clear understanding of the techniques presented here will facilitate effective simulation approaches leading to better solutions without compromising system performance. With contributions from Robert Ashton, Jeffrey Dunnihoo, Micheal Hopkins, Pratik Maheshwari, David Pomerenke, Wolfgang Reinprecht, and Matti Usumaki, readers benefit from hands-on experience and in-depth knowledge in topics ranging from ESD design and the physics of system ESD phenomena to tools and techniques to address soft failures and strategies to design ESD-robust systems that include mobile and automotive applications. The first dedicated resource to system-level ESD co-design, this is an essential reference for industry ESD designers, system builders, IC suppliers and customers and also Original Equipment Manufacturers (OEMs). Key features: Clarifies the concept of system level ESD protection. Introduces a co-design approach for ESD

robust systems. Details soft and hard ESD fail mechanisms. Detailed protection strategies for both mobile and automotive applications. Explains simulation tools and methodology for system level ESD co-design and overviews available test methods and standards. Highlights economic benefits of system ESD co-design.

* Examines the various methods available for circuit protection, including coverage of the newly developed ESD circuit protection schemes for VLSI circuits. * Provides guidance on the implementation of circuit protection measures. * Includes new sections on ESD design rules, layout approaches, package effects, and circuit concepts. * Reviews the new Charged Device Model (CDM) test method and evaluates design requirements necessary for circuit protection.

This Book and Simulation Software Bundle Project Dear Reader, this book project brings to you a unique study tool for ESD protection solutions used in analog-integrated circuit (IC) design. Quick-start learning is combined with in-depth understanding for the whole spectrum of cro- disciplinary knowledge required to excel in the ESD ?eld. The chapters cover technical material from elementary semiconductor structure and device levels up to complex analog circuit design examples and case studies. The book project provides two different options for learning the material. The printed material can be studied as any regular technical textbook. At the same time, another option adds parallel exercise using the trial version of a complementary commercial simulation tool with prepared simulation examples. Combination of the textbook material with numerical simulation experience presents a unique opportunity to gain a level of expertise that is hard to achieve otherwise. The book is bundled with simpli?ed trial version of commercial mixed- TM mode simulation software from Angstrom Design Automation. The DECIMM (Device Circuit Mixed-Mode) simulator tool and complementary to the book s- ulation examples can be downloaded from www.analogesd.com. The simulation examples prepared by the authors support the speci?c examples discussed across the book chapters. A key idea behind this project is to provide an opportunity to not only study the book material but also gain a much deeper understanding of the subject by direct experience through practical simulation examples.

This book addresses key aspects of analog integrated circuits and systems design related to system level electrostatic discharge (ESD) protection. It is an invaluable reference for anyone developing systems-on-chip (SoC) and systems-on-package (SoP), integrated with system-level ESD protection. The book focuses on both the design of semiconductor integrated circuit (IC) components with embedded, on-chip system level protection and IC-system co-design. The readers will be enabled to bring the system level ESD protection solutions to the level of integrated circuits, thereby reducing or completely eliminating the need for additional, discrete components on the printed circuit board (PCB) and meeting system-level ESD requirements. The authors take a systematic approach, based on IC-system ESD protection co-design. A detailed description of the available IC-level ESD testing methods is provided, together with a discussion of the

correlation between IC-level and system-level ESD testing methods. The IC-level ESD protection design is demonstrated with representative case studies which are analyzed with various numerical simulations and ESD testing. The overall methodology for IC-system ESD co-design is presented as a step-by-step procedure that involves both ESD testing and numerical simulations.

Electrical overstress (EOS) and Electrostatic discharge (ESD) pose one of the most dominant threats to integrated circuits (ICs). These reliability concerns are becoming more serious with the downward scaling of device feature sizes. Modeling of Electrical Overstress in Integrated Circuits presents a comprehensive analysis of EOS/ESD-related failures in I/O protection devices in integrated circuits. The design of I/O protection circuits has been done in a hit-or-miss way due to the lack of systematic analysis tools and concrete design guidelines. In general, the development of on-chip protection structures is a lengthy expensive iterative process that involves tester design, fabrication, testing and redesign. When the technology is changed, the same process has to be repeated almost entirely. This can be attributed to the lack of efficient CAD tools capable of simulating the device behavior up to the onset of failure which is a 3-D electrothermal problem. For these reasons, it is important to develop and use an adequate measure of the EOS robustness of integrated circuits in order to address the on-chip EOS protection issue. Fundamental understanding of the physical phenomena leading to device failures under ESD/EOS events is needed for the development of device models and CAD tools that can efficiently describe the device behavior up to the onset of thermal failure. Modeling of Electrical Overstress in Integrated Circuits is for VLSI designers and reliability engineers, particularly those who are working on the development of EOS/ESD analysis tools. CAD engineers working on development of circuit level and device level electrothermal simulators will also benefit from the material covered. This book will also be of interest to researchers and first and second year graduate students working in semiconductor devices and IC reliability fields.

Interest in latchup is being renewed with the evolution of complimentary metal-oxide semiconductor (CMOS) technology, metal-oxide-semiconductor field-effect transistor (MOSFET) scaling, and high-level system-on-chip (SOC) integration. Clear methodologies that grant protection from latchup, with insight into the physics, technology and circuit issues involved, are in increasing demand. This book describes CMOS and BiCMOS semiconductor technology and their sensitivity to present day latchup phenomena, from basic over-voltage and over-current conditions, single event latchup (SEL) and cable discharge events (CDE), to latchup domino phenomena. It contains chapters focusing on bipolar physics, latchup theory, latchup and guard ring characterization structures, characterization testing, product level test systems, product level testing and experimental results. Discussions on state-of-the-art semiconductor processes, design layout, and circuit level and system level latchup solutions are also included, as well as: latchup semiconductor process

solutions for both CMOS to BiCMOS, such as shallow trench, deep trench, retrograde wells, connecting implants, sub-collectors, heavily-doped buried layers, and buried grids – from single- to triple-well CMOS; practical latchup design methods, automated and bench-level latchup testing methods and techniques, latchup theory of logarithm resistance space, generalized alpha (a) space, beta (b) space, new latchup design methods– connecting the theoretical to the practical analysis, and; examples of latchup computer aided design (CAD) methodologies, from design rule checking (DRC) and logical-to-physical design, to new latchup CAD methodologies that address latchup for internal and external latchup on a local as well as global design level. Latchup acts as a companion text to the author's series of books on ESD (electrostatic discharge) protection, serving as an invaluable reference for the professional semiconductor chip and system-level ESD engineer. Semiconductor device, process and circuit designers, and quality, reliability and failure analysis engineers will find it informative on the issues that confront modern CMOS technology. Practitioners in the automotive and aerospace industries will also find it useful. In addition, its academic treatment will appeal to both senior and graduate students with interests in semiconductor process, device physics, computer aided design and design integration.

Electrostatic discharge (ESD) continues to impact semiconductormanufacturing, semiconductor components and systems, astechnologies scale from micro- to nano electronics. This bookintroduces the fundamentals of ESD, electrical overstress (EOS),electromagnetic interference (EMI), electromagnetic compatibility(EMC), and latchup, as well as provides a coherent overview of thesemiconductor manufacturing environment and the final systemassembly. It provides an illuminating look into the integration ofESD protection networks followed by examples in specifictechnologies, circuits, and chips. The text is unique in covering semiconductor chip manufacturingissues, ESD semiconductor chip design, and system problemsconfronted today as well as the future of ESD phenomena andnano-technology. Look inside for extensive coverage on: The fundamentals of electrostatics, triboelectric charging, andhow they relate to present day manufacturing environments ofmicro-electronics to nano-technology Semiconductor manufacturing handling and auditing processing toavoid ESD failures ESD, EOS, EMI, EMC, and latchup semiconductor component andsystem level testing to demonstrate product resilience from humanbody model (HBM), transmission line pulse (TLP), charged devicemodel (CDM), human metal model (HMM), cable discharge events (CDE),to system level IEC 61000-4-2 tests ESD on-chip design and process manufacturing practices andsolutions to improve ESD semiconductor chip solutions, alsopractical off-chip ESD protection and system level solutions toprovide more robust systems System level concerns in servers, laptops, disk drives, cellphones, digital cameras, hand held devices, automobiles, and spaceapplications Examples of ESD design for state-of-the-art technologies,including CMOS, BiCMOS, SOI, bipolar technology, high voltage

CMOS(HVCMOS), RF CMOS, smart power, magnetic recording technology,micro-machines (MEMs) to nano-structures ESD Basics: From Semiconductor Manufacturing to ProductUse complements the author's series of books on ESDprotection. For those new to the field, it is an essentialreference and a useful insight into the issues that confront moderntechnology as we enter the Nano-electronic Era.

Simulation Methods for ESD Protection Development looks at the integration of new techniques into a comprehensive development flow, which is now available due advances made in the field during the recent years. These findings allow for an early, stable ESD concept at a very early stage of the technology development, which is essential now development cycles have been reduced. The book also offers ways of increasing the optimization and control of the technology concerning performance, thus making the process more cost effective and increasingly efficient. This title provides a guide through the latest research and technology presenting the ESD protection development methodology. This is based on a combination of process, device and circuit stimulation, and addresses the optimization of the industry critical issue, reduced development cycles.Written to address the needs of the ESD engineer, this text is required reading by all industry practitioners and researchers and students within this field. The FIRST Extensive overview on the subject of ESD simulation Addresses the industry critical issue of reduced development cycles, and provides solutions Presents the latest research in the field with high practical relevance and its results

Electrostatic discharge (ESD) failure mechanisms continue to impact semiconductor components and systems as technologies scale from micro- to nano-electronics. This book studies electrical overstress, ESD, and latchup from a failure analysis and case-study approach. It provides a clear insight into the physics of failure from a generalist perspective, followed by investigation of failure mechanisms in specific technologies, circuits, and systems. The book is unique in covering both the failure mechanism and the practical solutions to fix the problem from either a technology or circuit methodology. Look inside for extensive coverage on: failure analysis tools, EOS and ESD failure sources and failure models of semiconductor technology, and how to use failure analysis to design more robust semiconductor components and systems; electro-thermal models and technologies; the state-of-the-art technologies discussed include CMOS, BiCMOS, silicon on insulator (SOI), bipolar technology, high voltage CMOS (HVCMOS), RF CMOS, smart power, gallium arsenide (GaAs), gallium nitride (GaN), magneto-resistive (MR) , giant magneto-resistors (GMR), tunneling magneto-resistor (TMR), devices; micro electro-mechanical (MEM) systems, and photo-masks and reticles; practical methods to use failure analysis for the understanding of ESD circuit operation, temperature analysis, power distribution, ground rule development, internal bus distribution, current path analysis, quality metrics, (connecting the theoretical to the practical analysis); the failure of each key element of a technology from passives, active elements to the circuit, sub-

system to package, highlighted by case studies of the elements, circuits and system-on-chip (SOC) in today's products. ESD: Failure Mechanisms and Models is a continuation of the author's series of books on ESD protection. It is an essential reference and a useful insight into the issues that confront modern technology as we enter the Nano-electronic era.

Neil Sclater offers practical advice on selecting test and control equipment, handling and storing semiconductors and other components, building static-free workstations, creating a protective environment for electronics, and much more. A complete listing of manufacturers and suppliers in included. Prior to founding his own electronics marketing research firm, Neil Sclater worked as an engineer for several leading corporations and as editor for Electronic Design and Product Engineering. He is the author of TPR's Gallium Arsenide IC Technology (No 3089).

Les défaillances induites par les décharges électrostatiques (ESD) constituent un problème majeur de fiabilité et de robustesse des circuits intégrés et des systèmes électroniques. Dans certaines applications comme celles de l'automobile, ce pourcentage peut être proche de 20 %. Les problèmes de défaillance catastrophiques induits par des décharges électrostatiques n'ont commencé à être sérieusement pris en compte qu'avec l'avènement des technologies microélectroniques et la large diffusion de leurs applications dans notre vie quotidienne. Cet ouvrage examine les diverses méthodologies de protection ESD et montre par le biais de cas concrets que la meilleure approche en termes de robustesse et de coût consiste à mettre en oeuvre une stratégie globale de protection ESD. Cette approche est déclinée du composant au système pour proposer des techniques d'investigation et des méthodologies de simulation prédictive associées, validées sur différents cas d'étude.

A practical and comprehensive reference that explores Electrostatic Discharge (ESD) in semiconductor components and electronic systems The ESD Handbook offers a comprehensive reference that explores topics relevant to ESD design in semiconductor components and explores ESD in various systems. Electrostatic discharge is a common problem in the semiconductor environment and this reference fills a gap in the literature by discussing ESD protection. Written by a noted expert on the topic, the text offers a topic-by-topic reference that includes illustrative figures, discussions, and drawings. The handbook covers a wide-range of topics including ESD in manufacturing (garments, wrist straps, and shoes); ESD Testing; ESD device physics; ESD semiconductor process effects; ESD failure mechanisms; ESD circuits in different technologies (CMOS, Bipolar, etc.); ESD circuit types (Pin, Power, Pin-to-Pin, etc.); and much more. In addition, the text includes a glossary, index, tables, illustrations, and a variety of case studies. Contains a well-organized reference that provides a quick review on a range of ESD topics Fills the gap in the current literature by providing information from purely scientific and physical aspects to practical applications Offers information in clear and accessible terms Written by

the accomplished author of the popular ESD book series Written for technicians, operators, engineers, circuit designers, and failure analysis engineers, The ESD Handbook contains an accessible reference to ESD design and ESD systems.
Praise for CMOS: Circuit Design, Layout, and SimulationRevised Second Edition from the Technical Reviewers "A refreshing industrial flavor. Design concepts are presented as they are needed for 'just-in-time' learning. Simulating and designing circuits using SPICE is emphasized with literally hundreds of examples. Very few textbooks contain as much detail as this one. Highly recommended!" --Paul M. Furth, New Mexico State University "This book builds a solid knowledge of CMOS circuit design from the ground up. With coverage of process integration, layout, analog and digital models, noise mechanisms, memory circuits, references, amplifiers, PLLs/DLLs, dynamic circuits, and data converters, the text is an excellent reference for both experienced and novice designers alike." --Tyler J. Gomm, Design Engineer, Micron Technology, Inc. "The Second Edition builds upon the success of the first with new chapters that cover additional material such as oversampled converters and non-volatile memories. This is becoming the de facto standard textbook to have on every analog and mixed-signal designer's bookshelf." --Joe Walsh, Design Engineer, AMI Semiconductor CMOS circuits from design to implementation CMOS: Circuit Design, Layout, and Simulation, Revised Second Edition covers the practical design of both analog and digital integrated circuits, offering a vital, contemporary view of a wide range of analog/digital circuit blocks, the BSIM model, data converter architectures, and much more. This edition takes a two-path approach to the topics: design techniques are developed for both long- and short-channel CMOS technologies and then compared. The results are multidimensional explanations that allow readers to gain deep insight into the design process. Features include: Updated materials to reflect CMOS technology's movement into nanometer sizes Discussions on phase- and delay-locked loops, mixed-signal circuits, data converters, and circuit noise More than 1,000 figures, 200 examples, and over 500 end-of-chapter problems In-depth coverage of both analog and digital circuit-level design techniques Real-world process parameters and design rules The book's Web site, CMOSedu.com, provides: solutions to the book's problems; additional homework problems without solutions; SPICE simulation examples using HSPICE, LTspice, and WinSpice; layout tools and examples for actually fabricating a chip; and videos to aid learning
This useful book addresses electrothermal problems in modern VLSI systems. It discusses electrothermal phenomena and the fundamental building blocks that electrothermal simulation requires. The authors present three important applications of VLSI electrothermal analysis: temperature-dependent electromigration diagnosis, cell-level thermal placement, and temperature-driven power and timing analysis.
With the evolution of semiconductor technology and global diversification of the semiconductor business, testing of semiconductor devices to systems for electrostatic discharge (ESD) and electrical overstress (EOS) has increased in

importance. ESD Testing: From Components to Systems updates the reader in the new tests, test models, and techniques in the characterization of semiconductor components for ESD, EOS, and latchup. Key features: Provides understanding and knowledge of ESD models and specifications including human body model (HBM), machine model (MM), charged device model (CDM), charged board model (CBM), cable discharge events (CDE), human metal model (HMM), IEC 61000-4-2 and IEC 61000-4-5. Discusses new testing methodologies such as transmission line pulse (TLP), to very fast transmission line pulse (VF-TLP), and future methods of long pulse TLP, to ultra-fast TLP (UF-TLP). Describes both conventional testing and new testing techniques for both chip and system level evaluation. Addresses EOS testing, electromagnetic compatibility (EMC) scanning, to current reconstruction methods. Discusses latchup characterization and testing methodologies for evaluation of semiconductor technology to product testing. ESD Testing: From Components to Systems is part of the authors' series of books on electrostatic discharge (ESD) protection; this book will be an invaluable reference for the professional semiconductor chip and system-level ESD and EOS test engineer. Semiconductor device and process development, circuit designers, quality, reliability and failure analysis engineers will also find it an essential reference. In addition, its academic treatment will appeal to both senior and graduate students with interests in semiconductor process, device physics, semiconductor testing and experimental work.